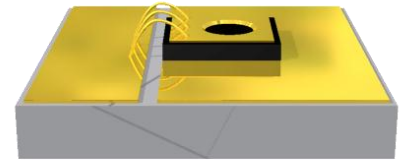


LASER DIODE SUB-MOUNT DESIGN GUIDELINES

Electro-Photonics offers submounts for photo diode and laser applications built to customer specifications. A laser die is normally mounted on a submount with similar CTE to prevent mechanical stress due to thermal expansion. To minimize the thermal effects and hence prevent damage to the laser, the submount material is chosen to have the proper thermal conductivity to dissipate the heat the laser generates. In consequence, the submount acts as a heat spreader. This submount can be further mounted onto a heat sink such as pure copper or copper-tungsten for increased thermal dissipation.



Refer to the tables below for design guidance. Please contact factory for special materials and/or custom metallization scheme. A DXF or DWG file format will be needed in order to provide a quote. Please send your files for RFQ to sales@electro-photonics.com.

TABLE 1: SELECTION

FEATURE	SPECIFICATION
SUBSTRATES	Aluminum Nitride Beryllium Oxide CVD Diamond
METALLIZATION	Ti / Pt / Au Pre-deposited Solder (Sn, AuSn) TaN Resist 50 and 100 Ohm/sq (±1%)
FEATURES	0.0025 in. lines and space (± 0.0005 in.) Thru-Hole and Wrap-Around capabilities
SIZE	.020 x .020 in. Area .005, .010, .015, and .025 in. Thicknesses (±10% standard, ±5% premium tolerance) 0.0005 Camber

TABLE 2: MATERIAL PROPERTIES

PROPERTY	ALUMINUM NITRIDE	BERYLLIUM OXIDE	CVD DIAMOND
THERMAL CONDUCTIVITY	170 W/mK *	270 W/mK	1000 W/mK
DIELECTRIC CONSTANT	8.6 @ 1MHz	6.5 @ 1MHz	5.7
DISSIPATION FACTOR	0.001 @ 1MHz	0.0004 @ 1MHz	0.0001 @ 1MHz
ELECTRICAL RESISTIVITY	>10 ¹⁴ Ωcm	>10 ¹⁴ Ωcm	>10 ¹⁴ Ωcm
THERMAL COEFFICIENT OF EXPANSION	4.6x10 ⁻⁶ (25 – 300°C)	9.0x10 ⁻⁶ (25 – 1000°C)	1.0x10 ⁻⁶ (25 – 300°C)
POLISHED SURFACE FINISH	<2 μ-in	<4 μ-in	<19.7 μ-in
DENSITY	3.28 g/cm ³	2.85 g/cm ³	3.515 g/cm ³

* Special 190 W/mK and 230 W/mK